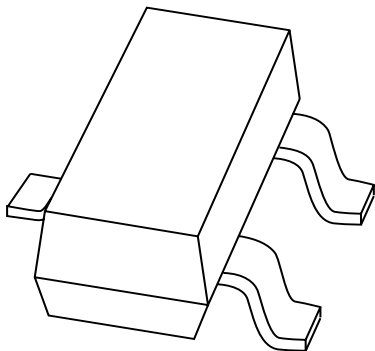


DATA SHEET



BF820; BF822 NPN high-voltage transistors

Product data sheet
Supersedes data of 1999 Apr 15

2004 Jan 16

NPN high-voltage transistors

BF820; BF822

FEATURES

- Low current (max. 50 mA)
- High voltage (max. 300 V).

APPLICATIONS

- Telephony and professional communication equipment.

DESCRIPTION

NPN high-voltage transistor in a SOT23 plastic package.
PNP complements: BF821; BF823.

MARKING

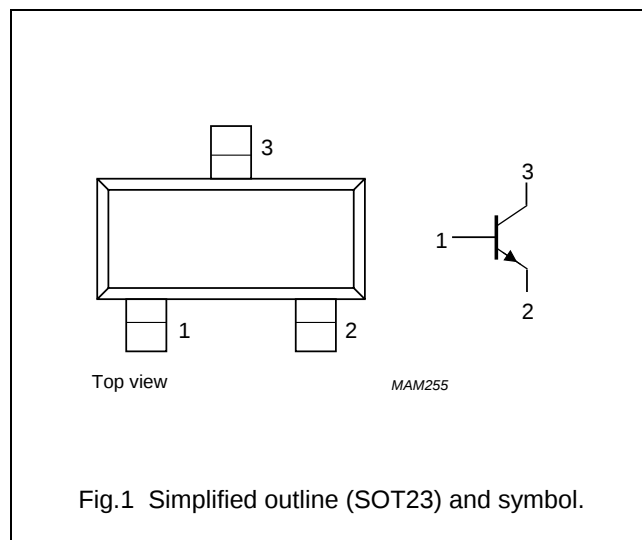
TYPE NUMBER	MARKING CODE ⁽¹⁾
BF820	1V*
BF822	1X*

Note

1. * = p : Made in Hong Kong.
 * = t : Made in Malaysia.
 * = W : Made in China.

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



ORDERING INFORMATION

TYPENUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BF820	—	plastic surface mounted package; 3 leads	SOT23
BF822	—	plastic surface mounted package; 3 leads	SOT23

NPN high-voltage transistors

BF820; BF822

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter			
	BF820		–	300	V
	BF822		–	250	V
V_{CEO}	collector-emitter voltage	open base			
	BF820		–	300	V
	BF822		–	250	V
V_{EBO}	emitter-base voltage	open collector	–	5	V
I_C	collector current (DC)		–	50	mA
I_{CM}	peak collector current		–	100	mA
I_{BM}	peak base current		–	50	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$; note 1	–	250	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	150	°C
T_{amb}	operating ambient temperature		–65	+150	°C

Note

1. Transistor mounted on an FR4 printed-circuit board.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

$T_j = 25\text{ °C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I_{CBO}	collector-base cut-off current	$I_E = 0$; $V_{CB} = 200\text{ V}$	–	10	nA
		$I_E = 0$; $V_{CB} = 200\text{ V}$; $T_j = 150\text{ °C}$	–	10	μA
I_{EBO}	emitter-base cut-off current	$I_C = 0$; $V_{EB} = 5\text{ V}$	–	50	nA
h_{FE}	DC current gain	$I_C = 25\text{ mA}$; $V_{CE} = 20\text{ V}$	50	–	
V_{CEsat}	collector-emitter saturation voltage	$I_C = 30\text{ mA}$; $I_B = 5\text{ mA}$	–	600	mV
C_{re}	feedback capacitance	$I_C = I_c = 0$; $V_{CB} = 30\text{ V}$; $f = 1\text{ MHz}$	–	1.6	pF
f_T	transition frequency	$I_C = 10\text{ mA}$; $V_{CE} = 10\text{ V}$; $f = 100\text{ MHz}$	60	–	MHz

NPN high-voltage transistors

BF820; BF822

PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads

SOT23

The diagrams illustrate the SOT23 package outline. The top view shows dimensions D (width) and B (lead width). The side view shows dimensions E (lead length), HE (height), and A (total height). A detail view 'X' shows the lead profile with dimensions A1, Q, c, and Lp. The bottom view shows dimensions 1, 2, 3 (lead positions), e1, bp, e, and a circular feature with dimensions w, v, and A. A scale bar indicates 0 to 2 mm.

DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max.	b _p	c	D	E	e	e ₁	H _E	L _p	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT23		TO-236AB				04-11-04 06-03-16

NPN high-voltage transistors

BF820; BF822

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

1. Please consult the most recently issued document before initiating or completing a design.
2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

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